



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-11-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	T107*AL6EB3F	A	Z8GA	2013-11-04
Amount	UoM	Unit type	ST ECOPACK Grade	
82.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MDF valid for STS7NF60L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	T107*AL6B3F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	4.67	mg	supplier	die	Silicon (Si)	7440-21-3		4.548	mg	973876	55463
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.081	mg	17345	988
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	214	12
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.04	mg	8565	488
Lead-frame	Other inorganic materials	31.929	mg	supplier	alloy	Copper(CU)	7440-50-8		30.875	mg	966989	376524
Lead-frame				supplier	alloy	Iron(Fe)	7439-89-6		0.745	mg	23333	9085
Lead-frame				supplier	alloy	Phosphorus(P)	7723-14-0		0.026	mg	814	317
Lead-frame				supplier	alloy	Zinc(Zn)	7440-66-6		0.04	mg	1253	488
Lead-frame				supplier	alloy	Silver(Ag)	7440-22-4		0.243	mg	7611	2963
Die Attach	Other inorganic materials	1.297	mg	supplier	glue	Silver (Ag)	7440-22-4		1.135	mg	875096	13841
Die Attach				supplier	glue	Bismaleimide resin	Proprietary		0.065	mg	50116	793
Die Attach				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.097	mg	74788	1183
Bonding wire	Precious metals	0.645	mg	supplier	wire	Gold(AU)	7440-57-5		0.645	mg	1000000	7866
Encapsulation	Other inorganic materials	39.656	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.966	mg	100010	48366
Encapsulation				supplier	mold compound	phenol resin	9003-35-4		1.586	mg	39994	19341
Encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.397	mg	10011	4841
Encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		32.517	mg	819977	396549
Encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.793	mg	19997	9671
Encapsulation				supplier	mold compound	Brominated epoxy resin	68928-70-1		0.397	mg	10011	4841
connections coating	Solder	3.803	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.803	mg	1000000	46378